

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc2657cfe-112#pbf

(Engineering Calculation)

TSSOP Exp. Pad

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TOTAL MASS (g) : 0.076612

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.006313 | 1000000 | 82401.8828125 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.024424 | 975000 | 318799.84375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000601 | 24000 | 7844.69042969 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000008 | 300 | 104.421829224 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000018 | 700 | 234.949127197 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.025051 | 1000000 | 326983.90625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001770 | 1000000 | 23107.6230469 | | |
| | | External Plating Total: | | | | 0.001770 | 1000000 | 23107.6230469 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000683 | 1000000 | 8915.01464844 | | |
| Internal Plating Total: | | | | 0.000683 | 1000000 | 8915.01464844 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001548 | 750000 | 20205.625 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000516 | 250000 | 6735.20800781 | | |
| Die Attach Total: | | | | 0.002064 | 1000000 | 26940.8320312 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.005414 | 135000 | 70667.4765625 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.034486 | 860000 | 450136.4375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000201 | 5000 | 2623.59863281 | | |
| | | Encapsulation Total: | | | | 0.040101 | 1000000 | 523427.5 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000630 | 1000000 | 8223.21972656 | | |
| | | | | | TOTAL MASS (g) : | 0.076612 | | |